Karta techniczna

31-07-2024 / V 1

Cechy i zalety

Warunki aplikacji — dodatkowe informacje

In above mentioned temperatures resin flow is optimized for best application effect and assumed material consumptions can be maintained.
During application and initial curing of product, substrate temperature needs to be at least 3 °C higher than dew point temperature.
In closed rooms a forced ventilation with at least 7-fold air exchange per hour is recommended.
Do not apply material in direct sunlight as it may prevent proper curing and cause inter-coat adhesion problems.
To assess possibility of application outside of these conditions or application temperatures below 0 °C, please consult our Technical Department.

Zużycie

~0.3 – 0.5 kg/m^2 w zależności od porowatości podłoża.

Wsparcie techniczne

W celu uzyskania wsparcia technicznego dot. aplikacji skontaktuj się z Tremco CPG Poland pod numerem +48 22 879 8907 lub napisz na poland@tremcocpg.com.

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